# 2 Port, USB 2.0 High Speed (480 Mbps) Switch, DPDT Analog Switch 

## DESCRIPTION

The DG2730 is 2 port high speed analog switch optimized for USB 2.0 signal switching. The DG2730 switch is configured in DPDT. It handles bidirectional signal flow, achieving a $900 \mathrm{MHz}-3 \mathrm{~dB}$ bandwidth, a port to port crosstalk at -36 dB and isolation at -29 dB , measured at 240 MHz .
Processed with high density sub micron CMOS, the DG2730 provide low parasitic capacitance. Signals are routed with minimized phase distortion and attain a bit to bit skew is as low as 40 ps .
The DG2730 is designed for a wide range of operating voltages, from 2.7 V to 5.5 V that can be driven directly from one cell Li-ion battery or 5 V power supply. On-chip circuitry protects against conditions when either the D+ / Dlines are shorted to the $\mathrm{V}_{\text {BUS }}$ at the USB port. Additionally, logic control pins ( S and OE ) can tolerate the presence of voltages that are above the supply power rail (V+). The control logic threshold is guaranteed to be ( $\mathrm{V}_{\mathrm{IH}}=1.3 \mathrm{~V} / \mathrm{min}$ up to $\mathrm{V}_{+}=3.6 \mathrm{~V}$ ). Latch up current is 500 mA , as per JESD78, and its ESD tolerance exceeds 5.5 kV .
Packaged in ultra small miniQFN-10 ( $1.4 \mathrm{~mm} \times 1.8 \mathrm{~mm} \times$ 0.55 mm ), it is ideal for portable high speed mix signal switching application.
As a committed partner to the community and the environment, Vishay Siliconix manufactures this product with lead (Pb)-free device termination. The miniQFN-10 package has a nickel-palladium-gold device termination and is represented by the lead (Pb)-free "-GE4" suffix to the ordering part number. The nickel-palladium-gold device terminations meet all JEDEC ${ }^{\circledR}$ standards for reflow and MSL rating.
As a further sign of Vishay Siliconix's commitment, the DG2730 is fully RoHS-complaint.

## FEATURES

- Wide operation voltage range
- Low on-resistance, $5.5 \Omega$ (typical at 3 V )
- Low capacitance, $\mathrm{C}_{\mathrm{ON}}=5.8 \mathrm{pF}$ (typical)
- 3 dB high bandwidth: 900 MHz (typical)
- Low bit to bit skew: 40 ps (typical)


RoHS COMPLIANT HALOGEN FREE

- Low power consumption
- Low logic threshold: V
- Power down protection: D+/D- pins can tolerate up to 5.5 V when $\mathrm{V}+=0 \mathrm{~V}$
- 5.5 kV ESD protection (HBM)
- Latch-up current 500 mA per JESD78
- Lead (Pb)-free low profile miniQFN-10 (1.4 mm x 1.8 mm $\times 0.55 \mathrm{~mm}$ )
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


## APPLICATIONS

- Cellular phones
- Portable media players
- PDA
- Digital camera
- GPS
- Notebook computer
- TV, monitor, and set top box


## FUNCTIONAL BLOCK DIAGRAM AND PIN CONFIGURATION

miniofn-10L


Device marking: 5x for DG2730
x = Date/Lot Traceability Code

| ORDERING INFROMATION |  |  |  |
| :---: | :---: | :---: | :---: |
| TEMP. RANGE | PACKAGE | PART NUMBER |  |
| $-40^{\circ} \mathrm{C}$ to $85^{\circ} \mathrm{C}$ | miniQFN-10 | DG2730DN-T1-GE4 |  |


| TRUTH TABLE |  |  |
| :---: | :---: | :---: |
| $\overline{\mathbf{O E}}$ (PIN 8) | $\mathbf{S}$ (PIN 10) | FUNCTION |
| 0 | 1 | D+ = HSD1+ and D- $=$ HSD1- |
| 0 | 0 | D+ = HSD2+ and D- $=$ HSD2- |
| 1 | X | Disconnect |


| PIN DESCRIPTIONS |  |
| :---: | :---: |
| PIN NAME | DESCRIPTION |
| $\overline{\mathrm{OE}}$ | Bus switch enable |
| S | Select input |
| $\mathrm{HSD} 1 \pm, \mathrm{HSD} 2 \pm, \mathrm{D} \pm$ | Data port |


| ABSOLUTE MAXIMUM RATINGS ( $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$, unless otherwise noted) |  |  |  |
| :---: | :---: | :---: | :---: |
| PARAMETER |  | LIMIT | UNIT |
| Reference to GND | V+ | -0.3 to 6 | V |
|  | S, $\overline{O E}, \mathrm{D}_{ \pm}, \mathrm{HSD}^{\prime} \pm$, HSD2 ${ }^{\text {a }}$ | -0.3 to (V+ + 0.3) |  |
| Current (Any Terminal Except S, $\overline{\mathrm{OE}}, \mathrm{D} \pm$, HSD1 $\pm$, HSD2 $\pm$ ) |  | 30 | mA |
| Continuous Current (S, OE, D $\pm$, HSD1 $\pm$, HSD2 $\pm$ ) |  | $\pm 250$ |  |
| Peak Current (Pulsed at $1 \mathrm{~ms}, 10 \%$ duty cycle) |  | $\pm 500$ |  |
| Storage Temperature (D suffix) |  | -65 to +150 | ${ }^{\circ} \mathrm{C}$ |
| Power Dissipation (Packages) ${ }^{\text {b }}$ | miniQFN-10 ${ }^{\text {c }}$ | 208 | mW |
| ESD (Human body model) |  | 5.5 | kV |
| Latch-Up (Current injection) |  | 500 | mA |

## Notes

a. Signals on $\mathrm{S}, \overline{\mathrm{OE}}, \mathrm{D} \pm, \mathrm{HSD} 1 \pm, \mathrm{HSD} 2 \pm$ exceeding $\mathrm{V}+$ will be clamped by internal diodes. Limit forward diode current to maximum current ratings.
b. All leads welded or soldered to PC board.
c. Derate $2.6 \mathrm{~mW} /{ }^{\circ} \mathrm{C}$ above $70^{\circ} \mathrm{C}$.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

DG2730
Vishay Siliconix

SPECIFICATIONS $(\mathrm{V}+=3 \mathrm{~V})$

| PARAMETER | SYMBOL | TEST CONDITIONS OTHERWISE UNLESS SPECIFIED | TEMP. ${ }^{\text {a }}$ | $\begin{gathered} \text { LIMITS } \\ -40^{\circ} \mathrm{C} \text { to }+85^{\circ} \mathrm{C} \end{gathered}$ |  |  | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | MIN. ${ }^{\text {b }}$ | TYP. ${ }^{\text {c }}$ | MAX. ${ }^{\text {b }}$ |  |
| Analog Switch |  |  |  |  |  |  |  |
| Analog Signal Range ${ }^{\text {d }}$ | $\mathrm{V}_{\text {ANALOG }}$ | $\mathrm{R}_{\mathrm{DS} \text { (on) }}$ | Full | 0 | - | V+ | V |
| On-Resistance | $\mathrm{R}_{\mathrm{DS} \text { (on) }}$ | $\mathrm{V}+=3 \mathrm{~V}, \mathrm{I}_{ \pm \pm}=8 \mathrm{~mA}, \mathrm{~V}_{\mathrm{HSD} 1 / 2 \pm}=0.4 \mathrm{~V}$ | Room | - | 5.5 | 8 | $\Omega$ |
|  |  |  | Full | - | - | 9 |  |
| On-Resistance Match ${ }^{\text {d }}$ | $\Delta \mathrm{R}_{\text {ON }}$ | $\mathrm{V}+=3 \mathrm{~V}, \mathrm{I}_{ \pm \pm}=8 \mathrm{~mA}, \mathrm{~V}_{\mathrm{HSD} 1 / 2 \pm}=0.4 \mathrm{~V}$ | Room | - | 0.8 | - |  |
| On-Resistance Flatness ${ }^{\text {d }}$ | RON Flatness | $\mathrm{V}+=3 \mathrm{~V}, \mathrm{I}_{ \pm \pm}=8 \mathrm{~mA}, \mathrm{~V}_{\mathrm{HSD} 1 / 2 \pm}=0 \mathrm{~V}, 1 \mathrm{~V}$ | Room | - | 2 | - |  |
| Switch Off Leakage Current | 1 off | $\begin{gathered} \mathrm{V}+=4.3 \mathrm{~V}, \mathrm{~V}_{\mathrm{HSD} 1 / 2 \pm}=0.3 \mathrm{~V}, 3 \mathrm{~V}, \\ \mathrm{~V}_{\mathrm{D} \pm}=3 \mathrm{~V}, 0.3 \mathrm{~V} \end{gathered}$ | Full | -100 | - | 100 | nA |
| Channel On Leakage Current | $\mathrm{I}_{\text {on }}$ | $\begin{gathered} \mathrm{V}+=4.3 \mathrm{~V}, \mathrm{~V}_{\mathrm{HSD} 1 / 2 \pm}=0.3 \mathrm{~V}, 4 \mathrm{~V}, \\ \mathrm{~V}_{\mathrm{D} \pm}=4 \mathrm{~V}, 0.3 \mathrm{~V} \end{gathered}$ | Full | -200 | - | 200 |  |
| Digital Control |  |  |  |  |  |  |  |
| Input Voltage High | $\mathrm{V}_{\text {INH }}$ | $\mathrm{V}+=3 \mathrm{~V}$ to 3.6 V | Full | 1.3 | - | - | V |
|  |  | $\mathrm{V}+=4.3 \mathrm{~V}$ | Full | 1.5 | - | - |  |
| Input Voltage Low | $\mathrm{V}_{\text {INL }}$ | $\mathrm{V}+=3 \mathrm{~V}$ to 4.3 V | Full | - | - | 0.5 |  |
| Input Capacitance | $\mathrm{C}_{\text {IN }}$ |  | Full | - | 6.5 | - | pF |
| Input Current | $\mathrm{l}_{\text {INL }}$ or $\mathrm{l}_{\text {INH }}$ | $\mathrm{V}_{\text {IN }}=0$ or $\mathrm{V}_{+}$ | Full | -1 | - | 1 | $\mu \mathrm{A}$ |
| Dynamic Characteristics |  |  |  |  |  |  |  |
| Break-Before-Make Time ${ }^{\text {d }}$ | $\mathrm{t}_{\text {BBM }}$ | $\begin{gathered} \mathrm{V}+=3 \mathrm{~V}, \mathrm{~V}_{\mathrm{D} 1 / 2 \pm}=1.5 \mathrm{~V}, \mathrm{R}_{\mathrm{L}}=50 \Omega, \\ \mathrm{C}_{\mathrm{L}}=35 \mathrm{pF} \end{gathered}$ | Room | - | 5 | - | ns |
|  |  |  | Full | - | 5 | - |  |
| S, $\overline{O E}$ Turn-On Time ${ }^{\text {d }}$ | $\mathrm{t}_{\mathrm{ON}}$ |  | Room | - | - | 30 |  |
|  |  |  | Full | - | - | 30 |  |
| S, $\overline{O E}$ Turn-Off Time ${ }^{\text {d }}$ | toff |  | Room | - | - | 25 |  |
|  |  |  | Full | - | - | 25 |  |
| Charge Injection ${ }^{\text {d }}$ | QinJ | $\mathrm{C}_{\mathrm{L}}=1 \mathrm{nF}, \mathrm{R}_{\mathrm{GEN}}=0 \Omega, \mathrm{~V}_{\mathrm{GEN}}=0 \mathrm{~V}$ | Room | - | 3 | - | pC |
| Off-Isolation ${ }^{\text {d }}$ | OIRR | $\begin{gathered} \mathrm{V}+=3 \mathrm{~V} \text { to } 3.6 \mathrm{~V}, \mathrm{R}_{\mathrm{L}}=50 \Omega, \mathrm{C}_{\mathrm{L}}=5 \mathrm{pF}, \\ \mathrm{f}=240 \mathrm{MHz} \end{gathered}$ |  | - | -29 | - | dB |
| Crosstalk d, e | $\mathrm{X}_{\text {TALK }}$ |  |  | - | -36 | - |  |
| Bandwidth d | BW | $\mathrm{V}+=3 \mathrm{~V}$ to $3.6 \mathrm{~V}, \mathrm{R}_{\mathrm{L}}=50 \Omega,-3 \mathrm{~dB}$ |  | - | 900 | - | MHz |
| D+/D- On Capacitance | $\mathrm{Con}^{\text {N }}$ | $\mathrm{V}+=3.3 \mathrm{~V}, \overline{\mathrm{OE}}=0 \mathrm{~V}, \mathrm{f}=240 \mathrm{MHz}$ |  | - | 5.8 | - |  |
| D1n, D2n Off Capacitance | $\mathrm{C}_{\text {OFF }}$ | $\mathrm{V}+=\overline{\mathrm{OE}}=3.3 \mathrm{~V}, \mathrm{f}=240 \mathrm{MHz}$ |  | - | 2.2 | - | P |
| Channel-to-Channel Skew ${ }^{\text {d }}$ | $\mathrm{t}_{\text {SK(0) }}$ | $\mathrm{V}+=3 \mathrm{~V}$ to $3.6 \mathrm{~V}, \mathrm{R}_{\mathrm{L}}=50 \Omega, \mathrm{C}_{\mathrm{L}}=5 \mathrm{pF}$ |  | - | 50 | - | ps |
| Skew Off Opposite Transitions of the Same Output ${ }^{d}$ | ${ }^{\text {SKK(p) }}$ |  |  | - | 20 | - |  |
| Total Jitter ${ }^{\text {d }}$ | $\mathrm{t}_{J}$ |  |  | - | 200 | - |  |
| Power Supply |  |  |  |  |  |  |  |
| Power Supply Range | V+ |  | - | 2.6 | - | 5.5 | V |
| Power Supply Current | I+ | $\mathrm{V}_{\text {IN }}=0 \mathrm{~V}$, or $\mathrm{V}_{+}$ | Full | - | - | 2 | $\mu \mathrm{A}$ |

## Notes

a. Room $=25^{\circ} \mathrm{C}$, Full $=$ as determined by the operating suffix.
b. The algebraic convention whereby the most negative value is a minimum and the most positive a maximum, is used in this datasheet.
c. Typical values are for design aid only, not guaranteed nor subject to production testing.
d. Guaranteed by design, not subjected to production test.
e. Crosstalk measured between channels.

TYPICAL CHARACTERISTICS $\left(\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}\right.$, unless otherwise noted)

$R_{\text {ON }}$ vs. $V_{D}$ and Single Supply Voltage


Ron vs. Analog Voltage and Temperature


RoN vs. Analog Voltage and Temperature

$R_{\text {ON }}$ vs. Analog Voltage and Temperature


Ron $_{\text {on }}$ vs. Analog Voltage and Temperature


Ron $_{\text {on }}$ vs. Analog Voltage and Temperature

Vishay Siliconix
TYPICAL CHARACTERISTICS $\left(\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}\right.$, unless otherwise noted)


Supply Current vs. Input Switching Frequency


Switching Threshold vs. Supply Voltage


Off-Isolation, $\mathrm{V}+=3.3 \mathrm{~V}$


Leakage Current vs. Temperature


Gain vs. Frequency, V+=3.3 V


Crosstalk, $\mathrm{V}_{+}=3.3 \mathrm{~V}$

## TEST CIRCUITS


$C_{L}$ (includes fixture and stray capacitance)

$$
\mathrm{V}_{\mathrm{OUT}}=\mathrm{D}_{ \pm}\left(\frac{\mathrm{R}_{\mathrm{L}}}{\mathrm{R}_{\mathrm{L}}+\mathrm{R}_{\mathrm{ON}}}\right)
$$



Logic "1" = Switch on
Logic input waveforms inverted for switches that have the opposite logic sense.

Fig. 1 - Switching Time


Fig. 2-Break-Before-Make Interval



IN depends on switch configuration: input polarity determined by sense of switch.

Fig. 3 - Charge Injection

## TEST CIRCUITS



Fig. 4-Off-Isolation


Fig. 5-Channel Off/On Capacitance

[^0]MINI QFN-10L CASE OUTLINE


| DIM | MILLIMETERS |  |  | INCHES |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  | MIN. | NAM. | MAX. | MIN. | NAM. | MAX. |
| A | 0.45 | 0.55 | 0.60 | 0.0177 | 0.0217 | 0.0236 |
| A1 | 0.00 | - | 0.05 | 0.000 | - | 0.002 |
| b | 0.15 | 0.20 | 0.25 | 0.006 | 0.008 | 0.010 |
| c | 0.150 or 0.127 REF ${ }^{(1)}$ |  |  | 0.006 or 0.005 REF ( ${ }^{(1)}$ |  |  |
| D | 1.70 | 1.80 | 1.90 | 0.067 | 0.071 | 0.075 |
| E | 1.30 | 1.40 | 1.50 | 0.051 | 0.055 | 0.059 |
| e | 0.40 BSC |  |  | 0.016 BSC |  |  |
| L | 0.35 | 0.40 | 0.45 | 0.014 | 0.016 | 0.018 |
| L1 | 0.45 | 0.50 | 0.55 | 0.0177 | 0.0197 | 0.0217 |

Note
${ }^{(1)}$ The dimension depends on the leadframe that assembly house used.

```
ECN T16-0163-Rev. B, 16-May-16
```

DWG: 5957

RECOMMENDED MINIMUM PADS FOR MINI QFN 10L


## Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.


[^0]:    Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?67786

